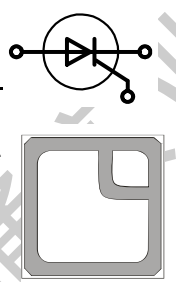


Type	Ag* Al*	V_{DRM} / V_{RRM}	V_{DSM} / V_{RSM} [V]	$I_{T(AV)}$ [A]	Chip Size [mm] x [mm]	Package Options	
CWP 30-12	<input checked="" type="checkbox"/> <input checked="" type="checkbox"/>	1200	1300	48	7.60 7.60	sawn on foil <input checked="" type="checkbox"/> unsawn wafer <input checked="" type="checkbox"/> * in waffle pack <input checked="" type="checkbox"/>	

*Frontside options

*Please contact IXYS chip sales

Mechanical Parameters

Area active	0.31	cm ²
Area total	0.58	cm ²
Wafer size Ø	150	mm
Thickness	290	µm
Material	Si	
Max. possible chips per wafer	227	
Passivation front side	Glassivation	
Metallization top side	solderable: Ti / Ni / Ag *	
top side	bondable: Al	
Recom. wire bonds (Al)	Cathode	Gate
* = <i>Stitchbonds</i> Number / Ø [µm]	7* / 500	1 / 500
Metallization backside	solderable (only): Ti / Ni / Ag *	
Reject Ink Dot Size	Ø 0.4-1.0	mm
Recom. Storage Environment		
sawn on foil	in org. container, in dry nitrogen	< 6 month
unsawn wafer	in org. container, in dry nitrogen	< 2 year
in waffle pack	in org. container, in dry nitrogen	< 2 year
	T_{stg}	-40 ... 40 °C

Features

- planar passivated with guardring and channelstopper
- Planar front and back surface
- Non-structured anode contact on full area bottom side

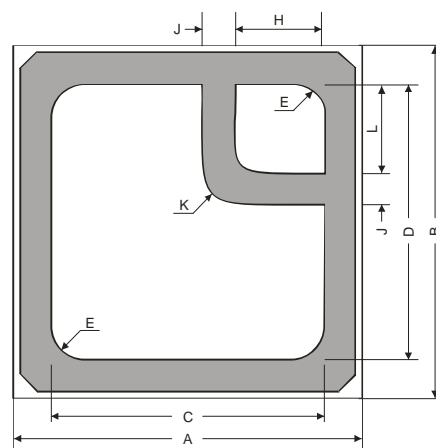
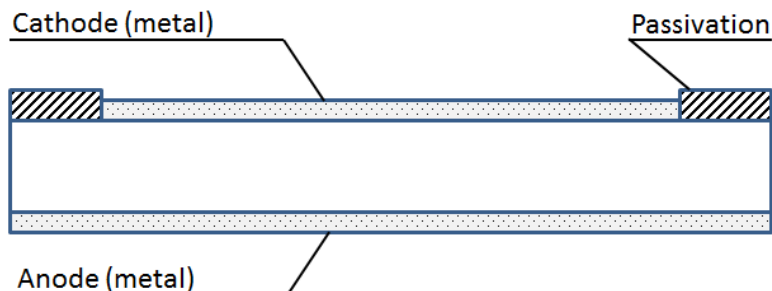
Applications

- DC motor control
- AC power control
- Softstart AC motor controller
- Light, heat and temperature control

*Sinterable top/bottom side on request

Dimensions

A	B	C	D	E	H	J	K	L
[mm]	[mm]	[mm]	[mm]	[mm]	[mm]	[mm]	[mm]	[mm]
7.60	7.60	6.00	6.00	0.34	1.50	0.40	0.40	1.50



Electrical parameters

Symbol	Conditions	Ratings		
		min.	typ.	max.
I_R	$V_D = V_r = V_{rr}$ $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$			0.05 mA 5 mA
V_T	$I_T = 115\text{ A}$ $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$			1.33 V 1.32 V
V_{T0}	For power-loss calculations only			0.9 V
r_T	$T_{VJ} = 150^\circ\text{C}$			3.50 mΩ
V_{GT}	$V_D = 6\text{ V}$ $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$			1.5 V 1.6 V
I_{GT}	$V_D = 6\text{ V}$ $T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = -40^\circ\text{C}$	25		38 mA 80 mA
V_{GD}	$T_{VJ} = 150^\circ\text{C}$ $V = \frac{2}{3} V_{DRM}$			0.2 V
I_{GD}				5 mA
I_L	$t_p = 10\ \mu\text{s}$ $T_{VJ} = 25^\circ\text{C}$ $I_G = 0.45\text{ A}$ $di_G/dt = 0.45\text{ A}/\mu\text{s}$			150 mA
I_H	$R_{GK} = \infty$ $T_{VJ} = 25^\circ\text{C}$ $V_D = 6\text{ V}$			100 mA
t_{gd}	$V_D = \frac{1}{2} V_{DRM}$ $T_{VJ} = 25^\circ\text{C}$ $I_G = 0.5\text{ A}$ $di_G/dt = 0.5\text{ A}/\mu$			2 μs
t_q	$V_R = 100\text{ V}$ $I_T = 40\text{ A}$ $-di/dt = 20\text{ A}/\mu\text{s}$ $t_p = 200\ \mu\text{s}$ $dv/dt = \text{V}/\mu\text{s}$ $V_D = \frac{2}{3} V_{DRM}$ $T_{VJ} = 125^\circ\text{C}$			150 μs
$(di/dt)_{cr}$	repetitive $I_T = 75\text{ A}$ non repetitive $I_T = 48\text{ A}$ $V = \frac{2}{3} V_{DRM}$ $T_{VJ} = 150^\circ\text{C}$ $di_G/dt = 0.45\text{ A}/\mu\text{s}$ $I_G = 0.45\text{ A}$ $t_p = 200\ \mu\text{s}$ $f = 50\text{ Hz}$			150 A/μs 500 A/μs
$(dv/dt)_{cr}$	$T_{VJ} = 150^\circ\text{C}$ $V_{DR} = \frac{2}{3} V_{DRM}$ $R_{GK} = \infty$ method 1 (linear voltage rise)			1000 V/μs
P_{GM}	$T_{VJ} = 150^\circ\text{C}$ $t_p = 30\ \mu\text{s}$ $t_p = 3E\ \mu\text{s}$			10 W 5 W
P_{GAV}				0.5 W
V_{RGM}				10 V
T_{VJ}		-40		150 °C
$I_{T(AV)}$	$T_C = 75^\circ\text{C}$ 180° rect. $T_{VJ} = 125^\circ\text{C}$ 180° sine			48 A 46 A
I_{TSM}^*	$T_{VJ} = 45^\circ\text{C}$ $t = 10\text{ ms}$ (50) Hz, sine $V_R = 0\text{ V}$ $t = 8.3\text{ ms}$ (60) Hz, sine $T_{VJ} = 150^\circ\text{C}$ $t = 10\text{ ms}$ (50) Hz, sine $V_R = 0\text{ V}$ $t = 8.3\text{ ms}$ (60) Hz, sine			1000 A 1100 A 850 A 920 A
I^2t^*	$T_{VJ} = 45^\circ\text{C}$ $t = 10\text{ ms}$ (50) Hz, sine $V_R = 0\text{ V}$ $t = 8.3\text{ ms}$ (60) Hz, sine $T_{VJ} = 150^\circ\text{C}$ $t = 10\text{ ms}$ (50) Hz, sine $V_R = 0\text{ V}$ $t = 8.3\text{ ms}$ (60) Hz, sine			5000 A s ² 5022 A s ² 3613 A s ² 3513 A s ²
R_{thJC}^*	DC current		0.85	K/W

* Data according to assembled product (solderable) tbd

Data according to IEC 60747

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- to perform joint risk and quality assessments;
- the conclusion of quality agreements;
- to establish joint measures to ensure application specific product capabilities and notify that IXYS may delivery dependent on the realization of any such measures.